

Claims:

- Sub 917
1. A method for reducing contamination inside a container including a plastic material, comprising coating selected portions of the plastic material of the container with a coating that includes titanium dioxide.
 2. The method of claim 1, wherein the container is especially adapted for holding semiconductor wafers, and wherein the selected portions are interior surfaces of the container.
 3. The method of claim 1, further comprising selecting the plastic material so that the plastic material includes polypropylene.
 4. The method of claim 1, further comprising selecting the plastic material so that the plastic material includes polycarbonate.
 5. A method for reducing contamination in a container including a plastic material, comprising coating selected portions of the container with a coating that is adapted to be relatively hydrophilic, wherein said coating is further adapted to decompose organic molecules into gases.
 6. The method of claim 5, further comprising selecting the plastic material so that the plastic material includes polypropylene.

